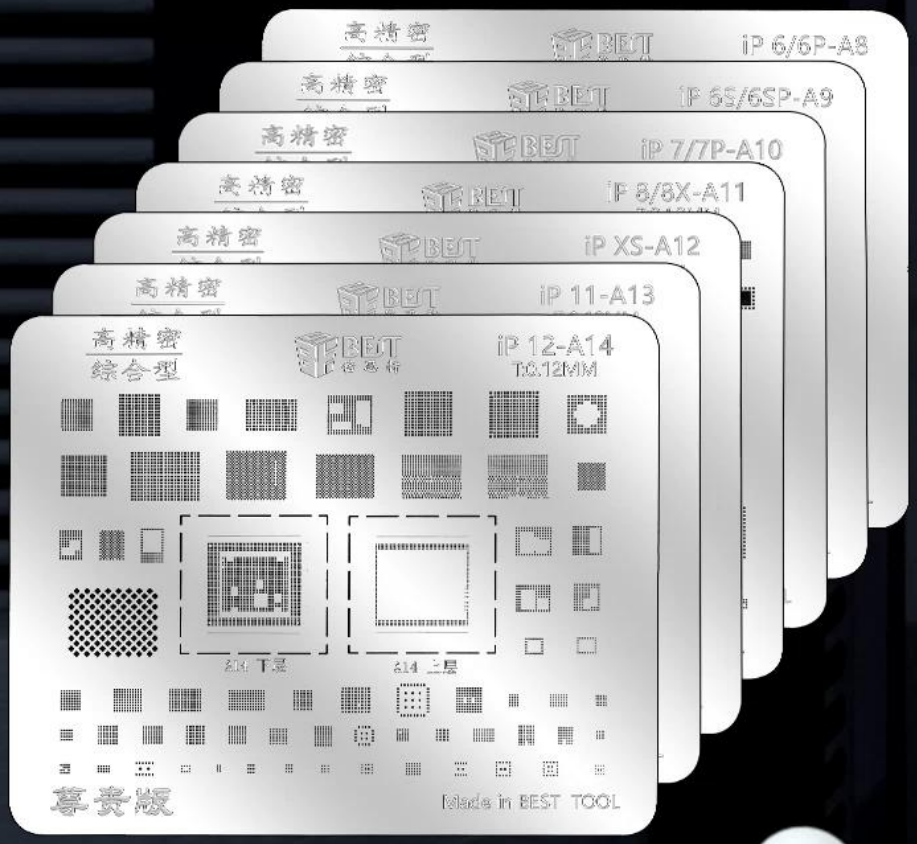
BGA IC

SOLDERING REBALLING STENCIL

High toughness

Strong magnetic steel



Product Usage

Model NO.	BST-iP (A8-A14)	Melting point	700℃
Name	Reballing Stencil	G.W.	25.8g
Material	Strong magnetic steel	Size	141*103*13.1mm

Four characteristics

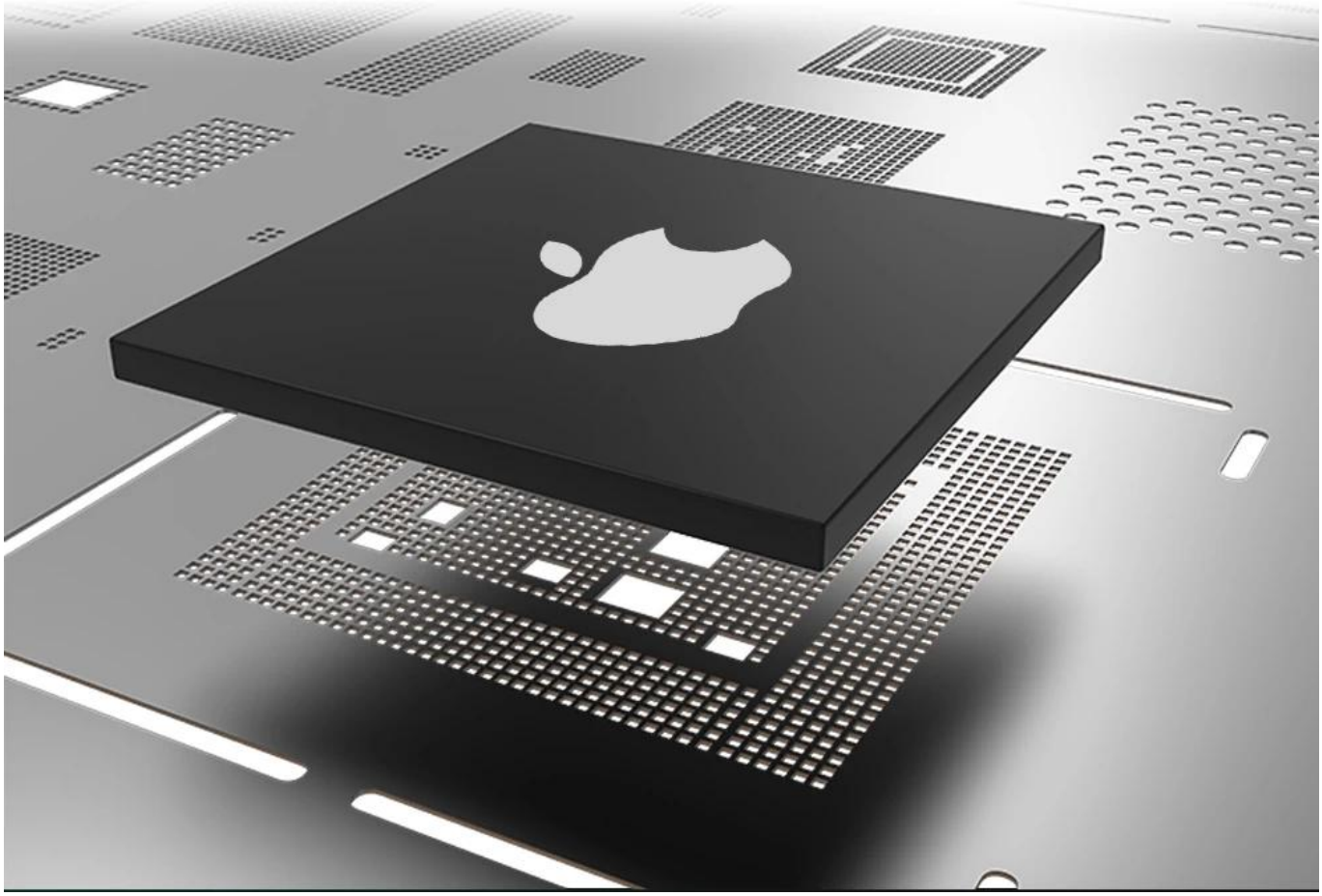
Semi-etching process

Cooling hole design

Square hole

Precise alignment

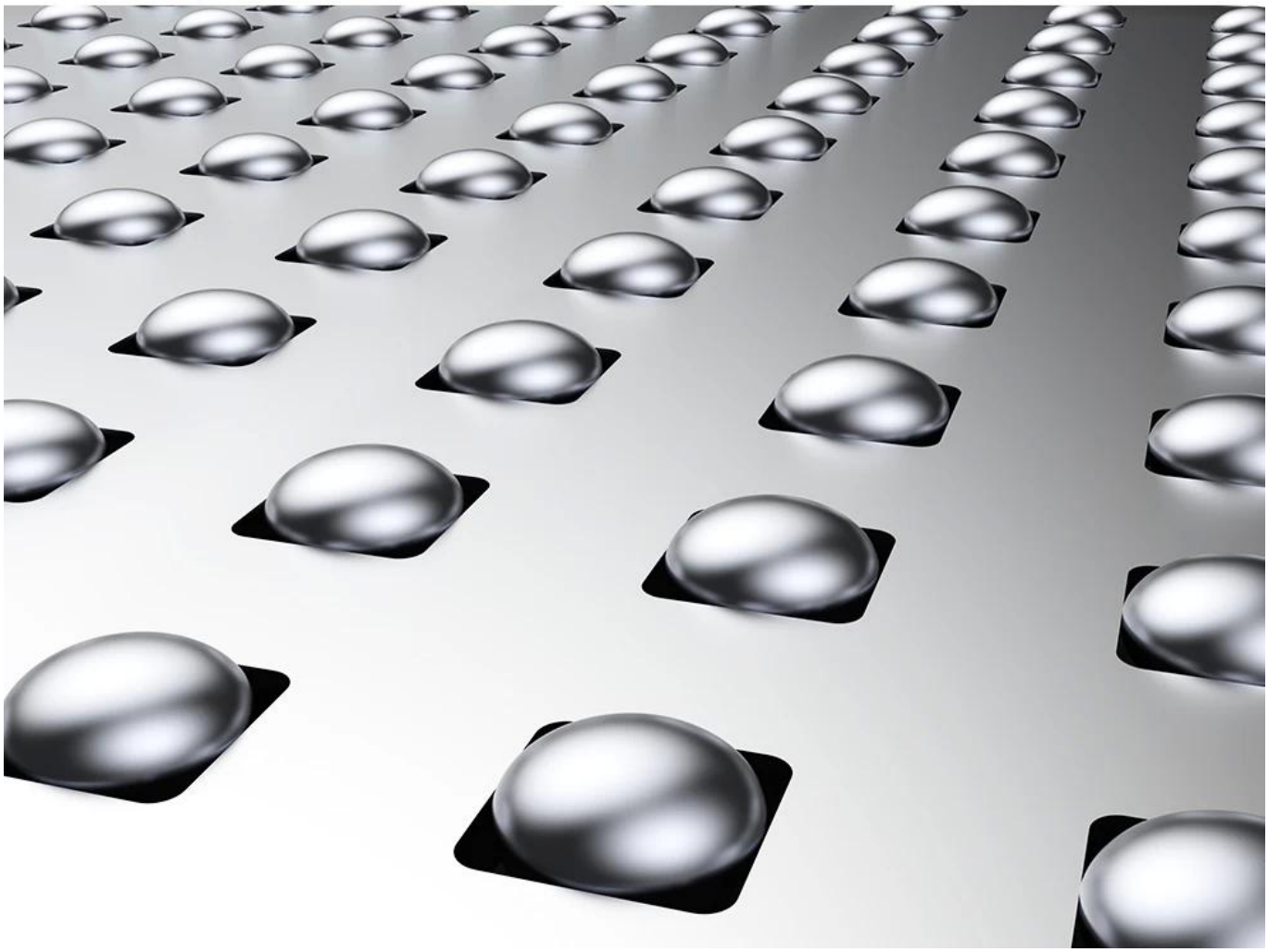
Easily mounted on the steel mesh to make the chip fit more closely with the mesh Therefore.



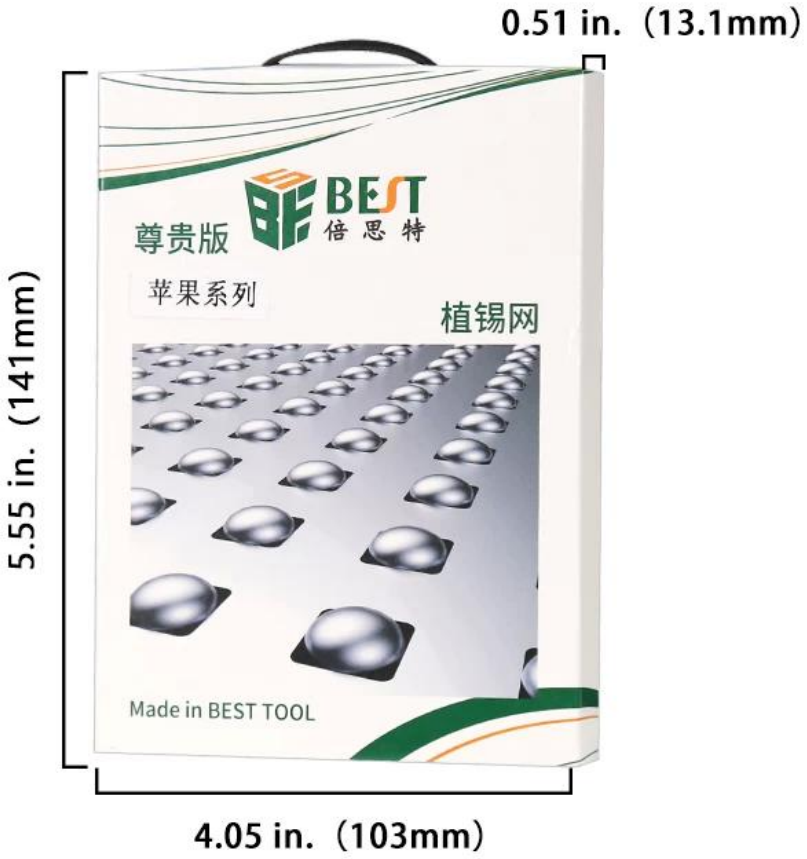
Hard and wear resistant
vertical hole position, no burr

Precision Reballing Stencil

Tin point is neat and tidy



G.W.:25.8G


0.51 in.（13.1mm）
5.55 in.（141mm）
BEST
倍思特
尊贵版
苹果系列
植锡网
Made in BEST TOOL
4.05 in.（103mm）